

CLAIMS

1. An integrated circuit (IC1) comprising functional logic (1) and Flash-EEPROM (2) coupled to at least one connection pad of said integrated circuit,

5 **characterized in that** several connection pads (CP1, CP2) are arranged into a pad arrangement (PAD: PAD1, PAD2, PAD3, PAD4),

and in that said integrated circuit (IC1) further comprises mixing devices (IMUX, OMUX) adapted to couple said functional logic (1) and said Flash-EEPROM (2) to a connection pad of said pad arrangement
10 (PAD).

2. The integrated circuit according to claim 1,

characterized in that said pad arrangement (PAD) comprises at least two juxtaposed connection pads (CP1, CP2) interconnected
15 electrically.

3. The integrated circuit according to claim 2,

characterized in that said two juxtaposed connection pads (CP1, CP2) have substantially the same design.
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4. The integrated circuit according to claim 1,

characterized in that said pad arrangement (PAD) comprises a first connection pad (CP1) adapted to be used for probing and for bonding, and a second connection pad (CP2) adapted to be used only for probing.
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5. An integrated circuit (IC2) comprising functional logic (1) and Flash-EEPROM (2) coupled to at least one connection pad of said integrated circuit,

characterized in that said integrated circuit (IC2) further
30 comprises a first set of dedicated connection pads (PAD10, PAD11, PAD12)

coupled to said functional logic (1), and a second set of dedicated connection pads (PAD21, PAD22) coupled to said Flash-EEPROM (2).

6. The integrated circuit according to any of the claims 1 or 5,
5 **characterized in that** said functional logic (1) comprises analog
logic and digital logic.